

# CSD18543Q3A 60-V N-Channel NexFET™ Power MOSFET

## 1 Features

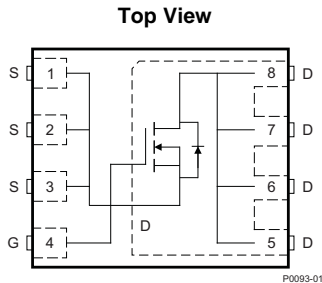
- Ultra-Low  $Q_g$  and  $Q_{gd}$
- Low  $R_{DS(on)}$
- Low-Thermal Resistance
- Avalanche Rated
- Lead Free
- RoHS Compliant
- Halogen Free
- SON 3.3-mm x 3.3-mm Plastic Package

## 2 Applications

- Solid State Relay Switch
- DC-DC Conversion
- Secondary Side Synchronous Rectifier
- Isolated Converter Primary Side Switch
- Motor Control

## 3 Description

This 60-V, 8.1-m $\Omega$ , SON 3.3-mm x 3.3-mm NexFET™ power MOSFET is designed to minimize losses in power conversion applications.



## Product Summary

$T_A = 25^\circ\text{C}$		TYPICAL VALUE		UNIT
$V_{DS}$	Drain-to-Source Voltage	60		V
$Q_g$	Gate Charge Total (10 V)	11.1		nC
$Q_{gd}$	Gate Charge Gate-to-Drain	1.7		nC
$R_{DS(on)}$	Drain-to-Source On Resistance	$V_{GS} = 4.5\text{ V}$	12.0	m $\Omega$
		$V_{GS} = 10\text{ V}$	8.1	
$V_{GS(th)}$	Threshold Voltage	2.0		V

## Device Information<sup>(1)</sup>

DEVICE	MEDIA	QTY	PACKAGE	SHIP
CSD18543Q3A	13-Inch Reel	2500	SON	Tape and Reel
CSD18543Q3AT	7-Inch Reel	250	3.30-mm x 3.30-mm Plastic Package	

(1) For all available packages, see the orderable addendum at the end of the data sheet.

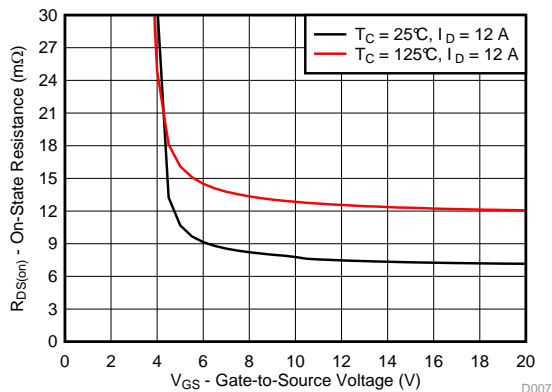
## Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$		VALUE	UNIT
$V_{DS}$	Drain-to-Source Voltage	60	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current (Package Limited)	35	A
	Continuous Drain Current (Silicon Limited), $T_C = 25^\circ\text{C}$	60	
	Continuous Drain Current <sup>(1)</sup>	12	
$I_{DM}$	Pulsed Drain Current <sup>(2)</sup>	156	A
$P_D$	Power Dissipation <sup>(1)</sup>	2.8	W
	Power Dissipation, $T_C = 25^\circ\text{C}$	66	
$T_J, T_{stg}$	Operating Junction, Storage Temperature	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Avalanche Energy, Single Pulse $I_D = 33\text{ A}, L = 0.1\text{ mH}, R_G = 25\ \Omega$	55	mJ

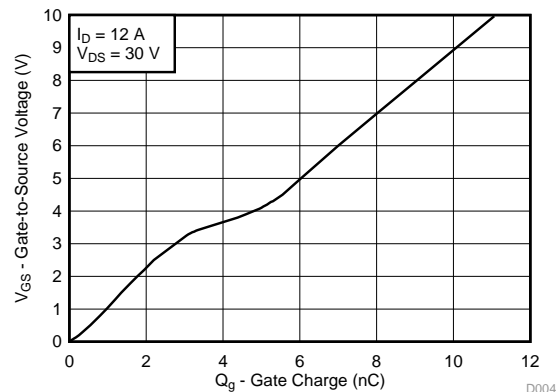
(1) Typical  $R_{\theta JA} = 45^\circ\text{C/W}$  on a 1-in<sup>2</sup>, 2-oz Cu pad on a 0.06-in thick FR4 PCB.

(2) Max  $R_{\theta JC} = 1.9^\circ\text{C/W}$ , pulse duration  $\leq 100\ \mu\text{s}$ , duty cycle  $\leq 1\%$ .

$R_{DS(on)}$  vs  $V_{GS}$



Gate Charge



## Table of Contents

<b>1 Features</b> ..... 1 <b>2 Applications</b> ..... 1 <b>3 Description</b> ..... 1 <b>4 Revision History</b> ..... 2 <b>5 Specifications</b> ..... 3 5.1 Electrical Characteristics..... 3 5.2 Thermal Information ..... 3 5.3 Typical MOSFET Characteristics..... 4 <b>6 Device and Documentation Support</b> ..... 7 6.1 Receiving Notification of Documentation Updates.... 7	6.2 Community Resources..... 7 6.3 Trademarks ..... 7 6.4 Electrostatic Discharge Caution ..... 7 6.5 Glossary ..... 7 <b>7 Mechanical, Packaging, and Orderable Information</b> ..... 8 7.1 Q3A Package Dimensions ..... 8 7.2 Q3A Recommended PCB Pattern ..... 9 7.3 Q3A Recommended Stencil Pattern ..... 10 7.4 Q3A Tape and Reel Information ..... 10
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## 4 Revision History

DATE	REVISION	NOTES
December 2016	*	Initial release.

## 5 Specifications

### 5.1 Electrical Characteristics

 $T_A = 25^\circ\text{C}$  (unless otherwise stated)

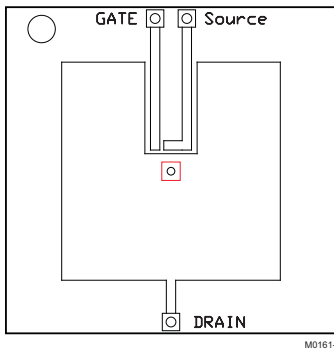
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>STATIC CHARACTERISTICS</b>						
$V_{DSS}$	Drain-to-source voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	60			V
$I_{DSS}$	Drain-to-source leakage current	$V_{GS} = 0\text{ V}, V_{DS} = 48\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate-to-source leakage current	$V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$			100	nA
$V_{GS(th)}$	Gate-to-source threshold voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1.5	2.0	2.7	V
$R_{DS(on)}$	Drain-to-source on resistance	$V_{GS} = 4.5\text{ V}, I_D = 12\text{ A}$		12.0	15.6	m $\Omega$
		$V_{GS} = 10\text{ V}, I_D = 12\text{ A}$		8.1	9.9	m $\Omega$
$g_{fs}$	Transconductance	$V_{DS} = 6\text{ V}, I_D = 12\text{ A}$		40		S
<b>DYNAMIC CHARACTERISTICS</b>						
$C_{iss}$	Input capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 30\text{ V}, f = 1\text{ MHz}$		885	1150	pF
$C_{oss}$	Output capacitance			168	218	pF
$C_{rss}$	Reverse transfer capacitance			4.8	6.2	pF
$R_G$	Series gate resistance			0.5	1.0	$\Omega$
$Q_g$	Gate charge total (4.5 V)	$V_{DS} = 30\text{ V}, I_D = 12\text{ A}$		5.6	7.3	nC
$Q_g$	Gate charge total (10 V)			11.1	14.5	
$Q_{gd}$	Gate charge gate-to-drain			1.7		nC
$Q_{gs}$	Gate charge gate-to-source			3.1		nC
$Q_{g(th)}$	Gate charge at $V_{th}$			2.0		nC
$Q_{oss}$	Output charge		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$		24	
$t_{d(on)}$	Turnon delay time	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V}, I_{DS} = 12\text{ A}, R_G = 0\ \Omega$		9		ns
$t_r$	Rise time			18		ns
$t_{d(off)}$	Turnoff delay time			8		ns
$t_f$	Fall time			4		ns
<b>DIODE CHARACTERISTICS</b>						
$V_{SD}$	Diode forward voltage	$I_{SD} = 12\text{ A}, V_{GS} = 0\text{ V}$		0.8	1.0	V
$Q_{rr}$	Reverse recovery charge	$V_{DS} = 30\text{ V}, I_F = 12\text{ A}, di/dt = 300\text{ A}/\mu\text{s}$		37		nC
$t_{rr}$	Reverse recovery time			27		ns

### 5.2 Thermal Information

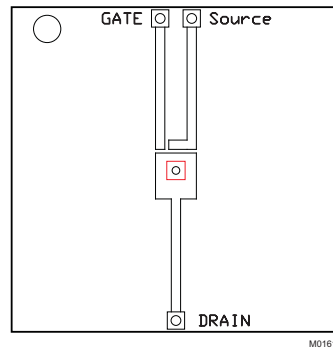
 $T_A = 25^\circ\text{C}$  (unless otherwise stated)

THERMAL METRIC		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-case thermal resistance <sup>(1)</sup>			1.9	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-ambient thermal resistance <sup>(1)(2)</sup>			55	

- (1)  $R_{\theta JC}$  is determined with the device mounted on a 1-in<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz (0.071-mm) thick Cu pad on a 1.5-in × 1.5-in (3.81-cm × 3.81-cm), 0.06-in (1.52-mm) thick FR4 PCB.  $R_{\theta JC}$  is specified by design, whereas  $R_{\theta JA}$  is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-in<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz (0.071-mm) thick Cu.



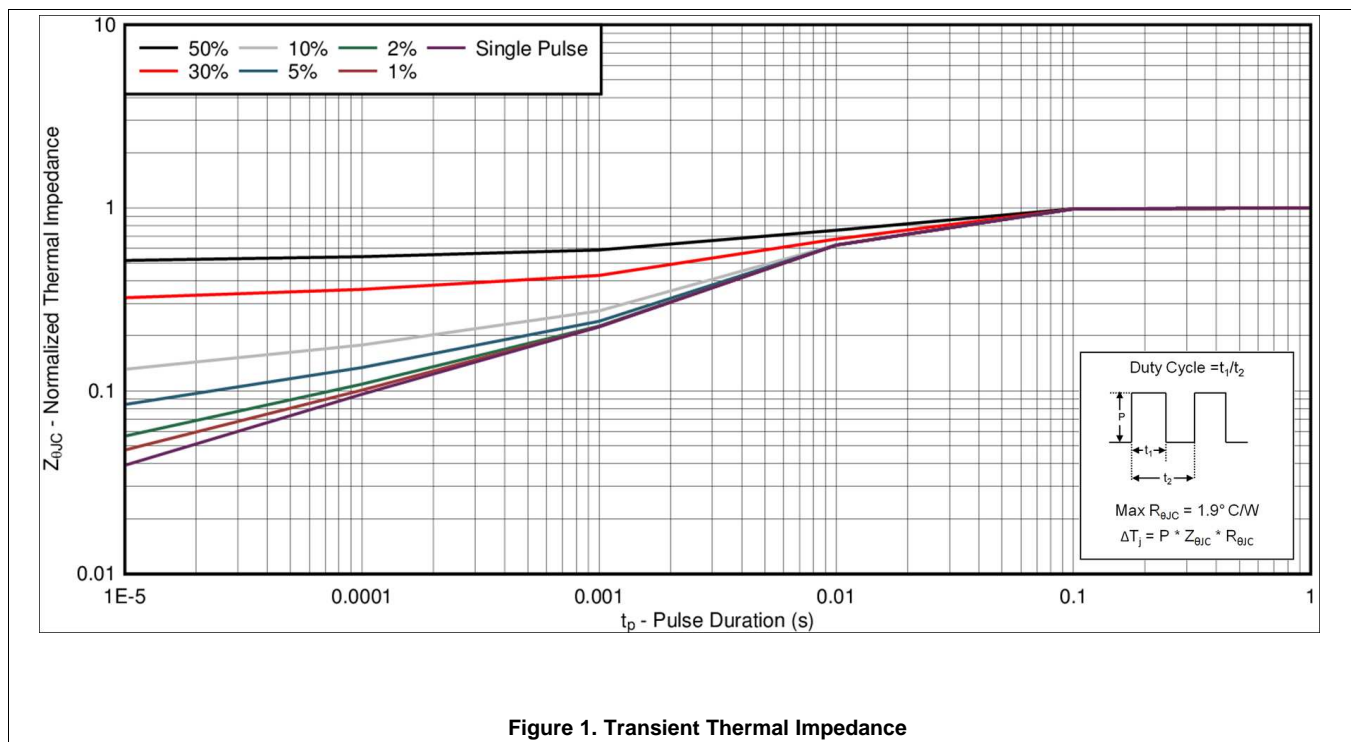
Max  $R_{\theta JA} = 55^{\circ}\text{C/W}$   
when mounted on 1 in<sup>2</sup>  
(6.45 cm<sup>2</sup>) of  
2-oz (0.071-mm) thick  
Cu.



Max  $R_{\theta JA} = 160^{\circ}\text{C/W}$   
when mounted on a  
minimum pad area of  
2-oz (0.071-mm) thick  
Cu.

### 5.3 Typical MOSFET Characteristics

$T_A = 25^{\circ}\text{C}$  (unless otherwise stated)



Typical MOSFET Characteristics (continued)

T<sub>A</sub> = 25°C (unless otherwise stated)

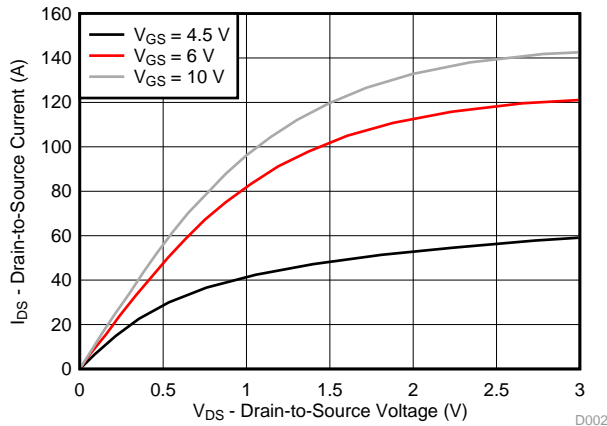


Figure 2. Saturation Characteristics

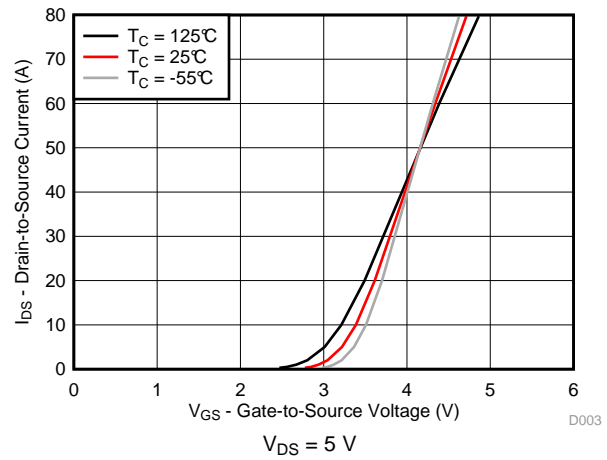


Figure 3. Transfer Characteristics

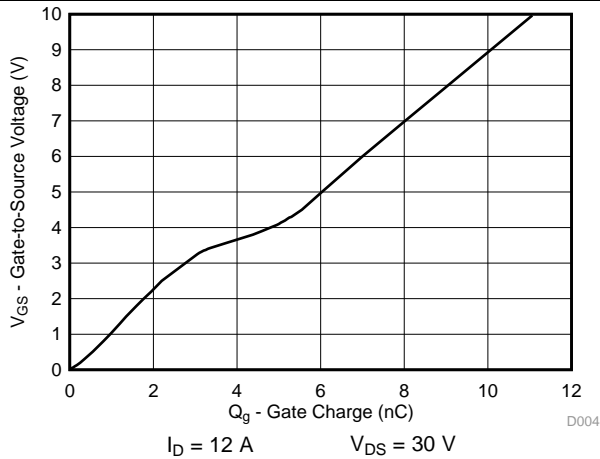


Figure 4. Gate Charge

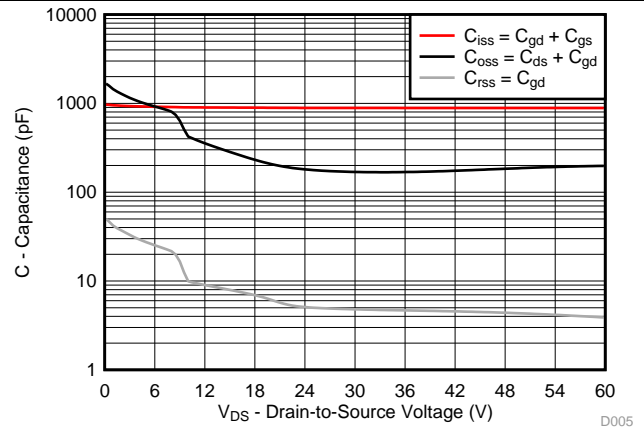


Figure 5. Capacitance

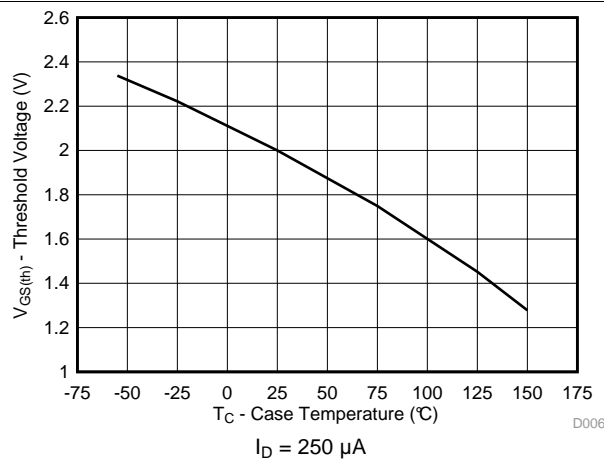


Figure 6. Threshold Voltage vs Temperature

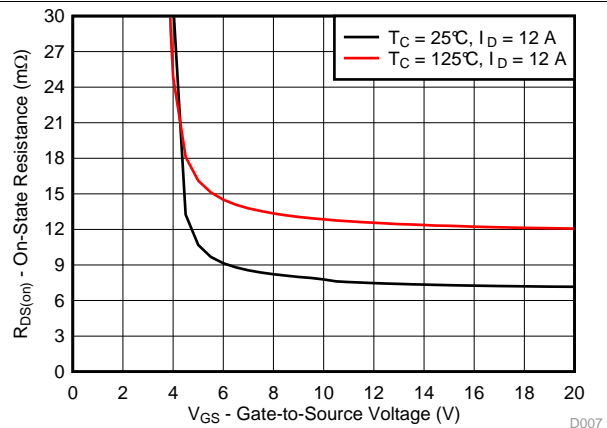


Figure 7. On-State Resistance vs Gate-to-Source Voltage

Typical MOSFET Characteristics (continued)

$T_A = 25^\circ\text{C}$  (unless otherwise stated)

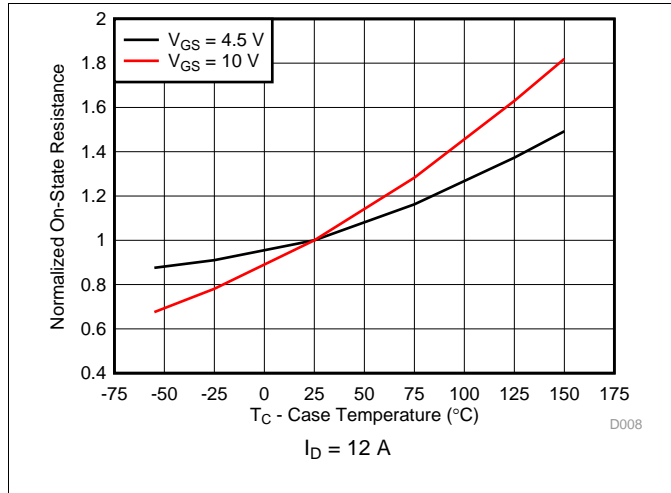


Figure 8. Normalized On-State Resistance vs Temperature

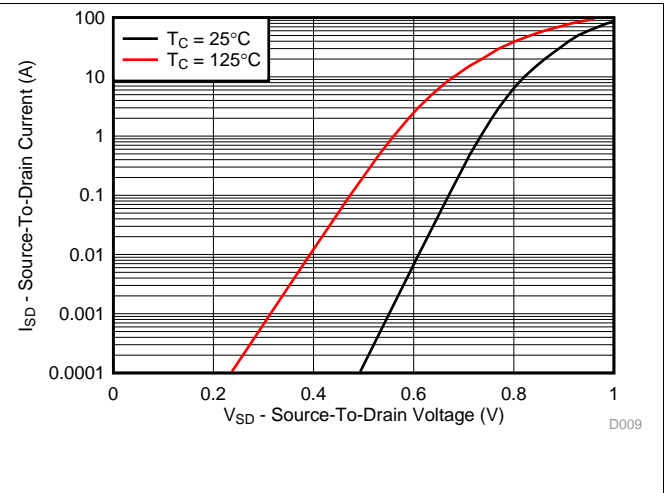


Figure 9. Typical Diode Forward Voltage

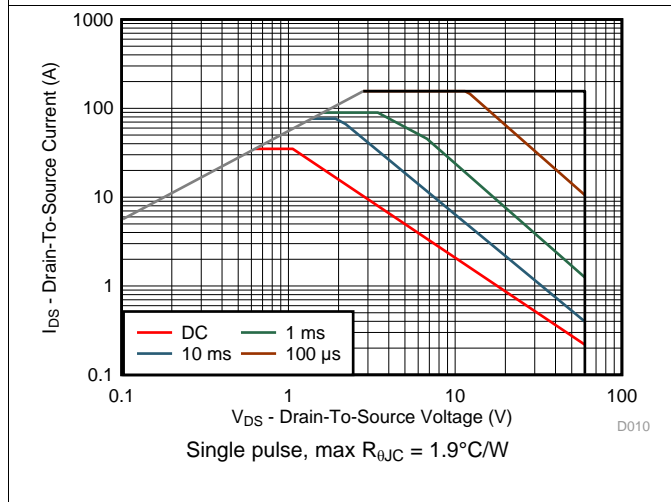


Figure 10. Maximum Safe Operating Area (SOA)

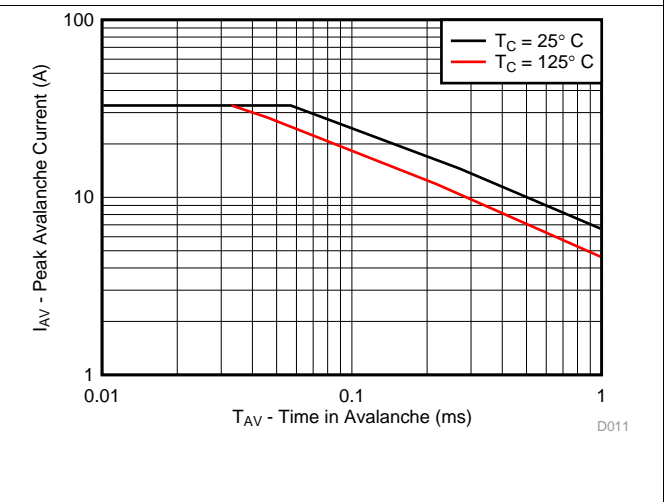


Figure 11. Single Pulse Unclamped Inductive Switching

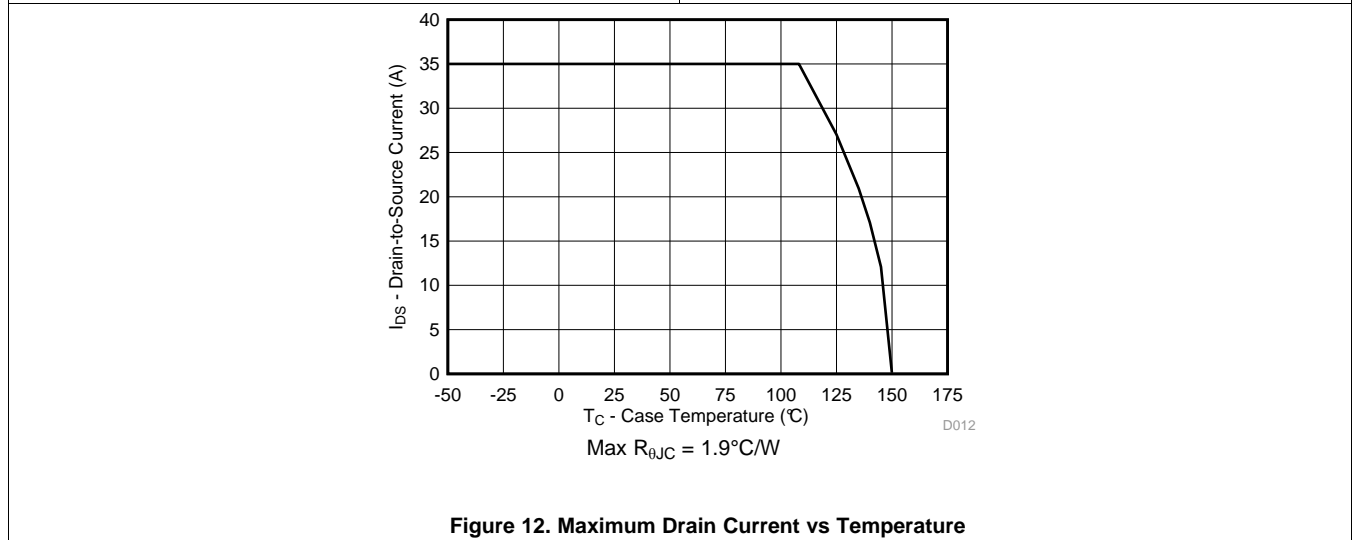


Figure 12. Maximum Drain Current vs Temperature

## 6 Device and Documentation Support

### 6.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 6.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 6.3 Trademarks

NexFET, E2E are trademarks of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 6.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 6.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

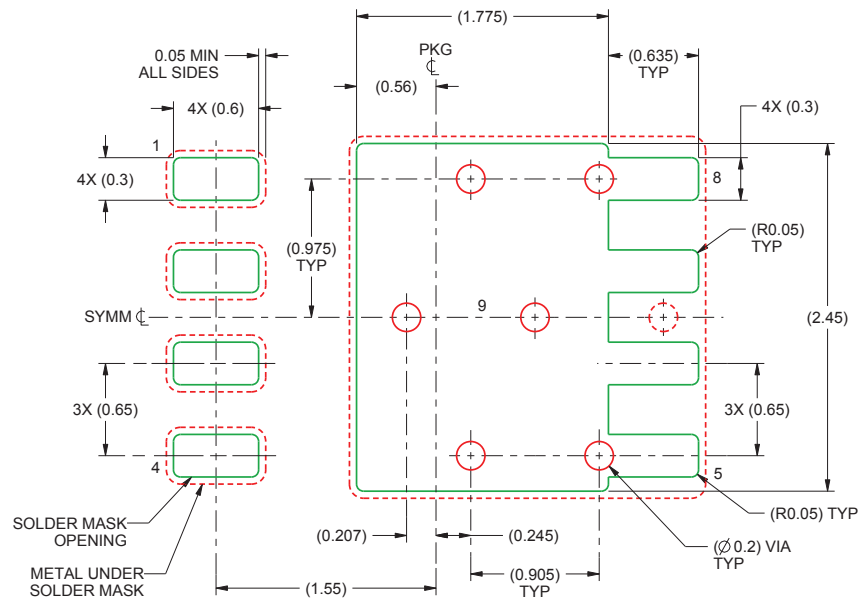
### 7.1 Q3A Package Dimensions



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Metalized features are supplier options and may not be on the package.
5. All dimensions do not include mold flash or protrusions.



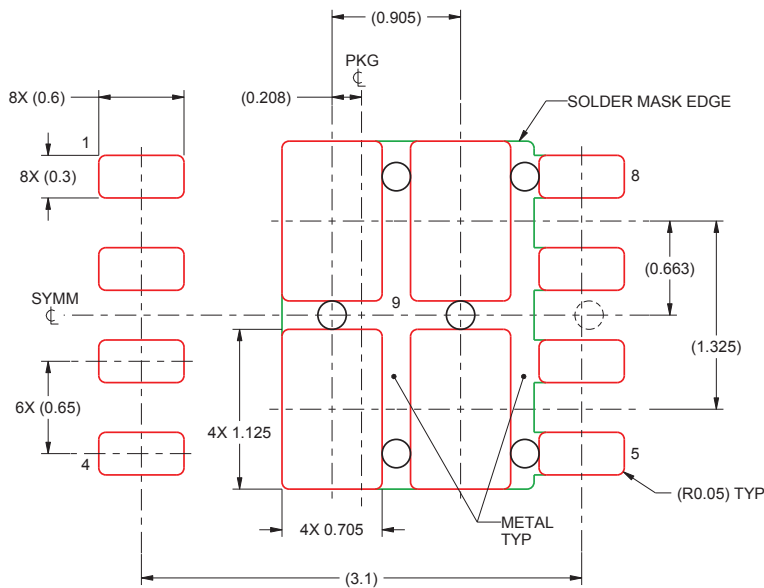
## 7.2 Q3A Recommended PCB Pattern



1. This package is designed to be soldered to a thermal pad on the board. For more information, see [QFN/SON PCB Attachment \(SLUA271\)](#).
2. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

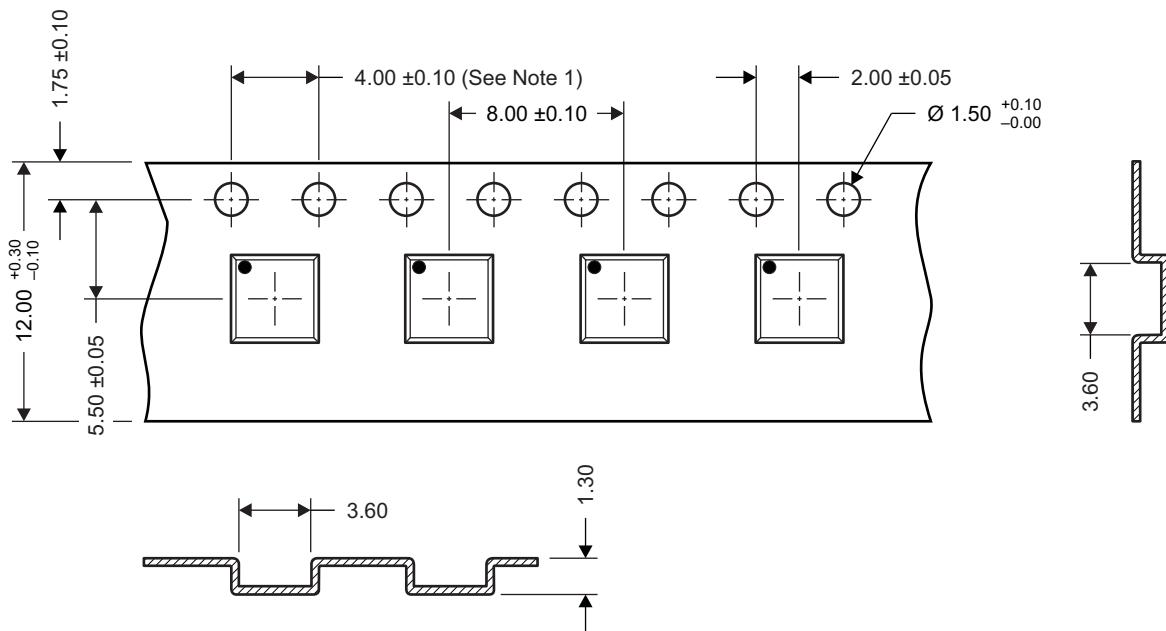
For recommended circuit layout for PCB designs, see [Reducing Ringing Through PCB Layout Techniques \(SLPA005\)](#).

### 7.3 Q3A Recommended Stencil Pattern



1. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

### 7.4 Q3A Tape and Reel Information



M0144-01

- Notes:
1. 10-sprocket hole-pitch cumulative tolerance  $\pm 0.2$ .
  2. Camber not to exceed 1 mm in 100 mm, noncumulative over 250 mm.
  3. Material: black static-dissipative polystyrene.
  4. All dimensions are in mm, unless otherwise specified.
  5. Thickness:  $0.30 \pm 0.05$  mm.
  6. MSL1 260°C (IR and convection) PbF-reflow compatible.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD18543Q3A	ACTIVE	VSONP	DNH	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-55 to 150	18543	<a href="#">Samples</a>
CSD18543Q3AT	ACTIVE	VSONP	DNH	8	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-55 to 150	18543	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

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